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General Information

Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	560 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Dimensions

Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
T	1mm +/-0.10mm
S	2.3mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

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